

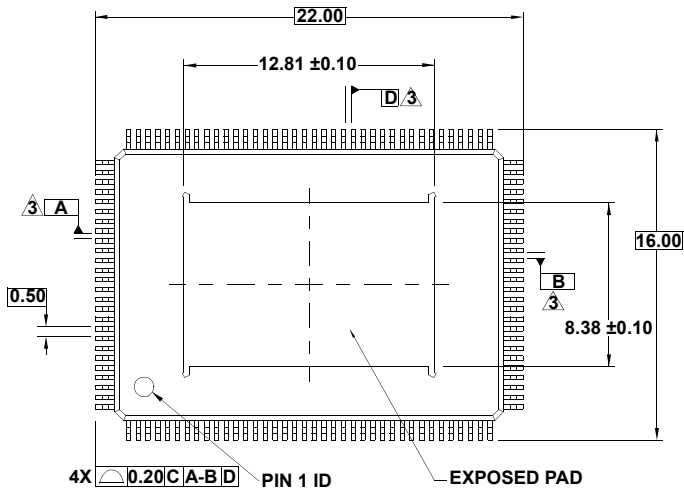
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

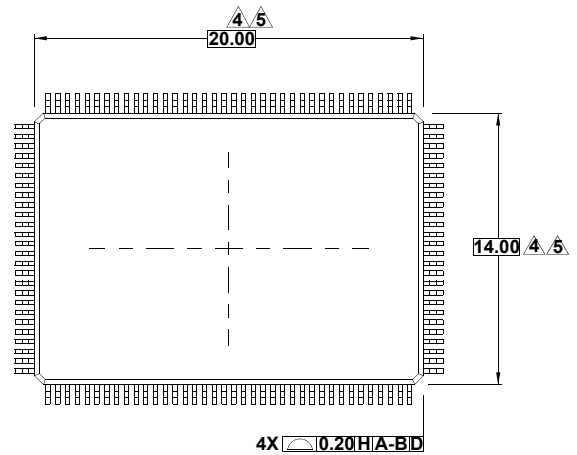
### Q128.14x20C

128 LOW PLASTIC QUAD FLATPACK PACKAGE WITH TOP EXPOSED PAD (TEP-LQFP)

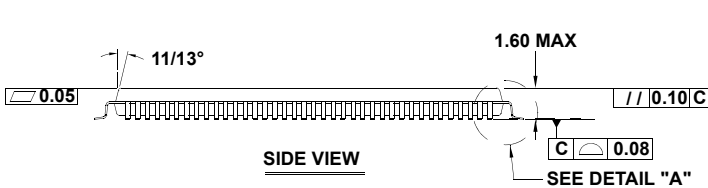
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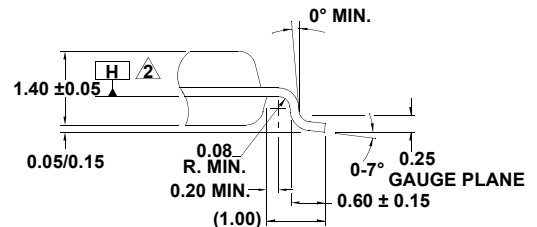
TOP VIEW



BOTTOM VIEW

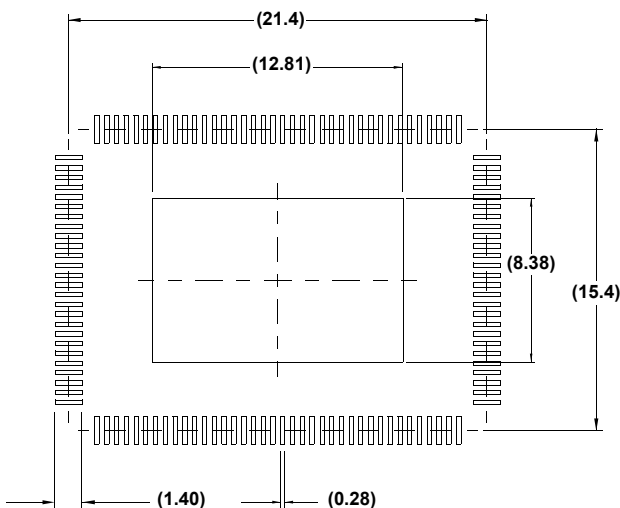


SIDE VIEW

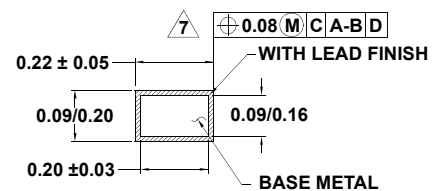


DETAIL "A"

SCALE: NONE



TYPICAL RECOMMENDED LAND PATTERN



#### NOTES:

- All dimensioning and tolerancing conform to ANSI Y14.5-1982.
- Datum plane H located at mold parting line and coincident with lead, where lead exits plastic body at bottom of parting line.
- Datums A-B and D to be determined at centerline between leads where leads exit plastic body at datum plane H.
- Dimensions do not include mold protrusion. Allowable mold protrusion is 0.254mm.
- These dimensions to be determined at datum plane H.
- Package top dimensions are smaller than bottom dimensions and top of package will not overhang bottom of package.
- Does not include dambar protrusion. Allowable dambar protrusion shall be 0.08mm total at maximum material condition. Dambar cannot be located on the lower radius or the foot.
- Controlling dimension: millimeter.
- This outline conforms to JEDEC publication 95 registration MS-026, variation BHB-HU.
- Dimensions in ( ) are for reference only.